

#2/Me-Hmt-A  
4/26-57  
JH

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of: : Docket: YOR919990336US2  
Chao-kun Hu et al. : Prior Group Art Unit: 2815  
Serial No.: To be Assigned : Prior Examiner: A. Wilson  
Filed: Herewith : Date: November 13, 2001  
For: REDUCED ELECTROMIGRATION AND STRESSED INDUCED MIGRATION  
OF Cu WIRES BY SURFACE COATING

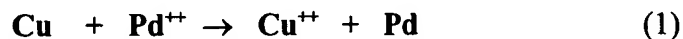
Preliminary Amendment

Commissioner for Patents  
Washington, D.C. 20231

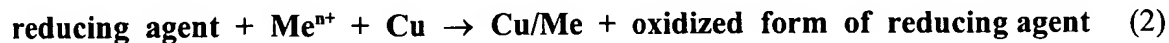
Sir:

In the Specification

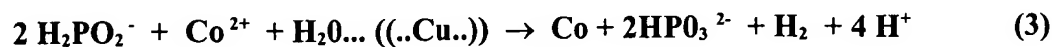
Please replace Equation 1 at page 3, line 19, with the following rewritten equation 1:



Please replace Equation 2 at page 4, line 5, with the following rewritten equation 2:



Please replace Equation 3 at page 4, line 9, with the following rewritten equation 3:



Docket No.: YOR919990336US2

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